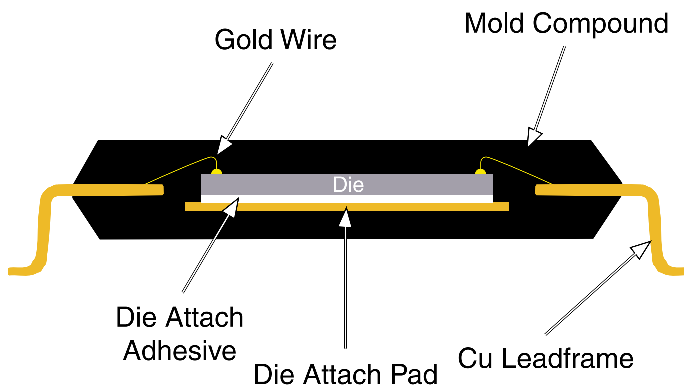
data sheet

TQFP

Cross-section TQFP



Process Highlights

Die thickness	11.5 ± .5 mils
Strip solder plating	85/15 Sn/Pb
Strip marking	Laser
Lead inspection	Laser/Optical
Pack/ship options	Bar code, dry pack
Wafer backgrinding	Available

Test Services

- Program generation/conversion
- Product engineering
- Wafer sort
- 256 pin x 20 MHz test system available
- -55 °C to +165 °C test available
- Burn-in

Shipping

JEDEC outline CO-124 low profile tray

Configuration Options:

TQFP NOMINAL PACKAGE DIMENSIONS (mm)

Body Size	Body Tkns	Lead Form	Standoff	Foot Length	Tip To Tip	Lead Count	JEDEC	Tray Matrix	Units Per Tray
5 x 5	1.00	1.00	0.10	0.60	7.0	32/40	MS-026	12 x 30	360
7 x 7	1.00	1.00	0.10	0.60	9.0	32/48	MS-026	10 x 25	250
10 x 10	1.00	1.00	0.10	0.60	12.0	44/52/64	MS-026	8 x 20	160
12 x 12	1.00	1.00	0.10	0.60	14.0	80	MS-026	7 x 17	119
14 x 14	1.00	1.00	0.10	0.60	16.0	44/64/80/100/120/128	MS-026	6 x 15	90
20 x 20	1.00	1.00	0.10	0.60	22.0	144/176	MS-026	5 x 12	60